

Specifications

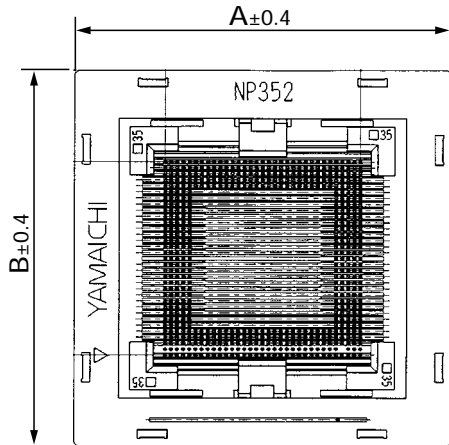
Insulation Resistance: 1,000MΩ min. at 100V DC
 Dielectric Withstanding Voltage: 100V AC for 1 minute
 Contact Resistance: 100mΩ max. at 10mA/20mV max.
 Operating Temperature Range: -40°C to +150°C / -55°C to +150°C
 Contact Force: 15g per pin approx.
 Mating Cycles: 10,000 insertions minimum



Materials and Finish

Housing: Polyetherimide (PEI), glass-filled
 Polyethersulphone (PES), glass-filled
 Contacts: Beryllium Copper (BeCu)
 Plating: Gold over Nickel

Outline Socket Dimensions



Part Number (Details)

NP352 - 1064 26 - * - *

Series No.

No. of Contact Pins

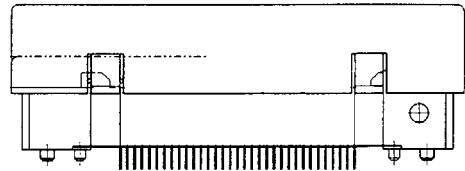
Design Number

Mark for Positioning Pins

Contact Terminal Lengths and Form

Features

- Open top type sockets with "Tweezer Style Contacts" For FBGA packages
- Secure package alignment due to self contacting structure without upper pressing force (ZIF)
- Contacting structure to nip the sides of solder balls to lower damages of coplanarity of solder balls

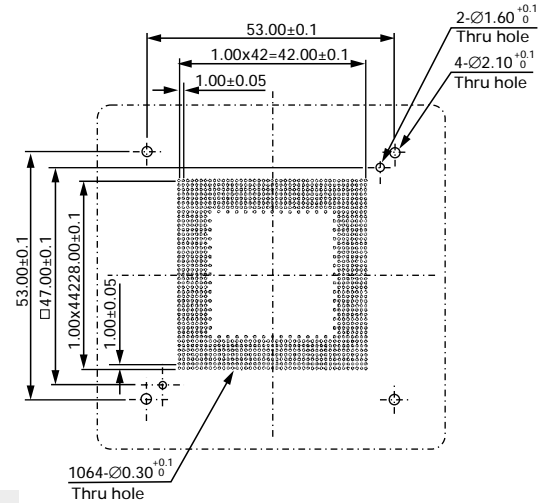
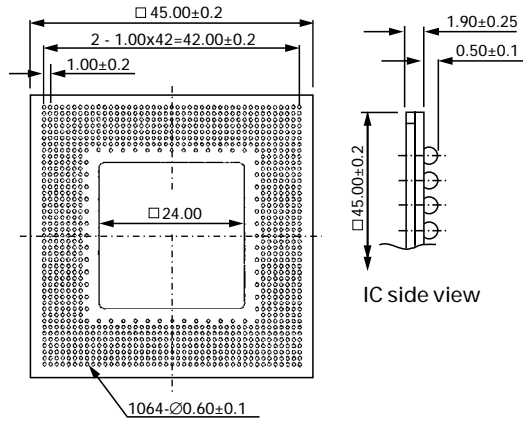


Part Number	Pin Count	IC Dimensions		Socket Dimensions A x B
		Grid Size	Body Size _(mm)	
NP352-106426-*	1064	43 x 43	45 x 45	74.0 x 74.0
NP352-115523	1155	34 x 34	35 x 35	62.0 x 62.0
NP352-1206-38	1206	36 x 36	37.5 x 37.5	62.0 x 62.0

Top View from Socket

1064 pins NP352-106426-*

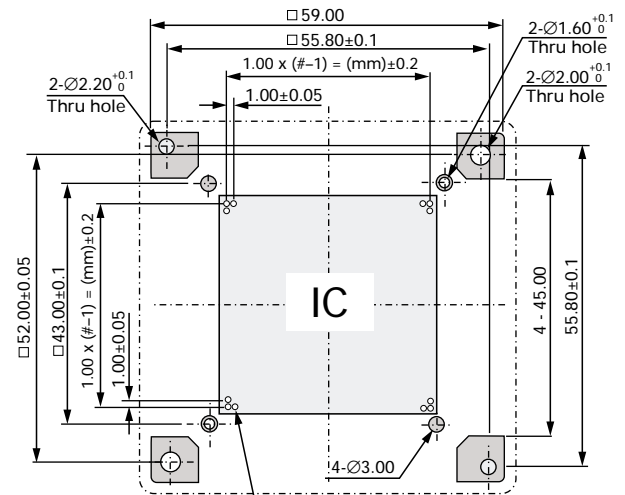
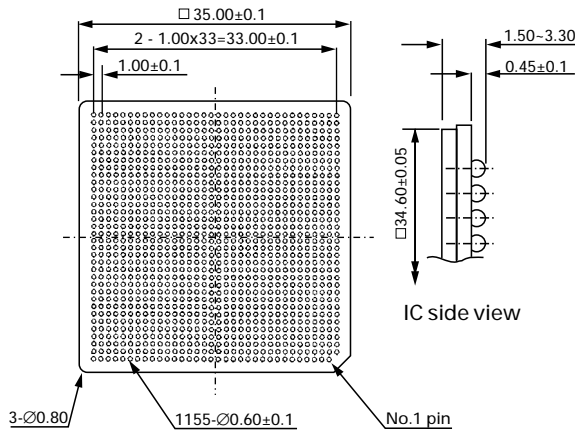
Recommended PCB Layout



Grid Size 43 x 43

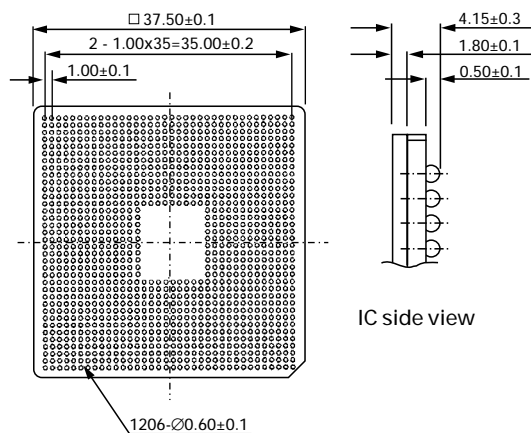
1155pins NP352-115523

Recommended PCB Layout



Grid Size 34 x 34

1206 pins NP352-1206-38



■ = Stand-off area (#)-∅0.30±0.1 Thru hole
 (#) = The number of pins

Grid Size 36 x 36